

Patent

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Customer No.: 31561
 Application No.: 10/707,609
 Docket No. 10073-US-PA

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Applicant : Chen et al.
 Application No. : 10/707,609
 Filed : December 24, 2003
 For : FLIP CHIP PACKAGE STRUCTURE
 Art Unit : 2814
 Examiner : TRINH, HOA B

TRANSMITTAL LETTER
 +1-571-273-8300
 (Via fax: 1+2+ 8 pages)

ASSISTANT COMMISSIONER FOR PATENTS
 Alexandria, VA 22314

Dear Sir,

In response to the Advisory Action dated August 22, 2005, please find the relevant papers as follows:

Request for Continued Examination in (2) pages;
 Preliminary Amendment in (8) pages.

Thank you for your assistance in the subject matter. If you have any questions, please feel free to contact me.

Respectfully Submitted,
 JIANQ CHYUN Intellectual Property Office

Date: Oct. 3, 2005

By: Belinda Lee
 Belinda Lee
 Registration No.: 46,863

Please send future correspondence to:
 7F. -1, No. 100, Roosevelt Rd.,
 Sec. 2, Taipei 100, Taiwan, R.O.C.
 Tel: 886-2-2369 2800 Fax: 886-2-2369 7233 / 886-2-2369 7234
 E-MAIL: BELINDA@JCIPGroup.com.tw; USA@JCIPGroup.com.tw

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